

Amendments to the Specification

In the first sentence of the specification please replace the phrase "Patent Application serial No. 10/231,636" with the phrase -Patent No. 6,686,221-.

Please replace the paragraph beginning on line 15 of page 10 with the following amended paragraph:

Referring now to Figures 3-4, ball grid array package substrate 10 is shown to include an array of solder balls 11 that are disposed on the top surface of ball grid array package substrate 10. Solder balls 11 electrically couple to ones of bonding pads 18-19. It is appreciated that the number and placement of solder balls in the present embodiment is illustrative and that the present invention is well adapted for the use of more or fewer solder balls 11 and different placement of solder balls 11. In one alternate embodiment, solder balls 11 are disposed on the bottom surface ~~49~~ 29 of ball grid array package substrate 10.